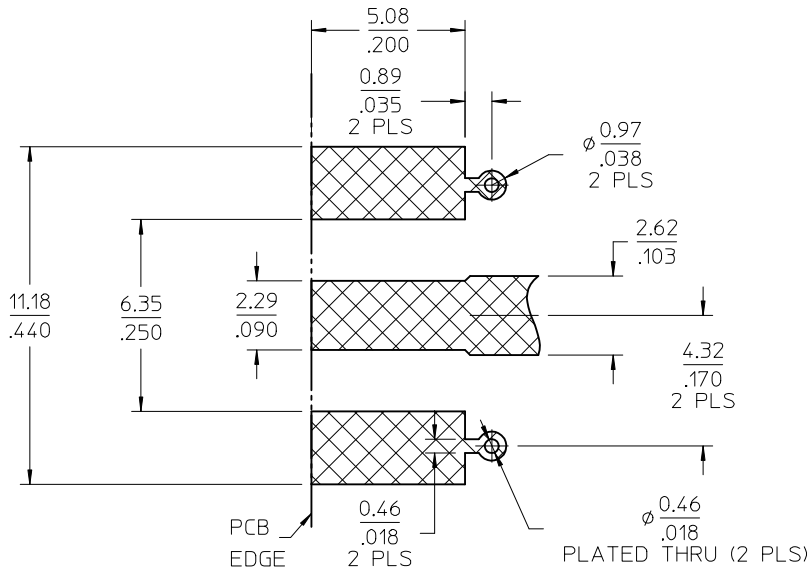
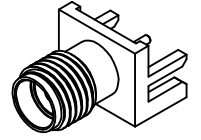
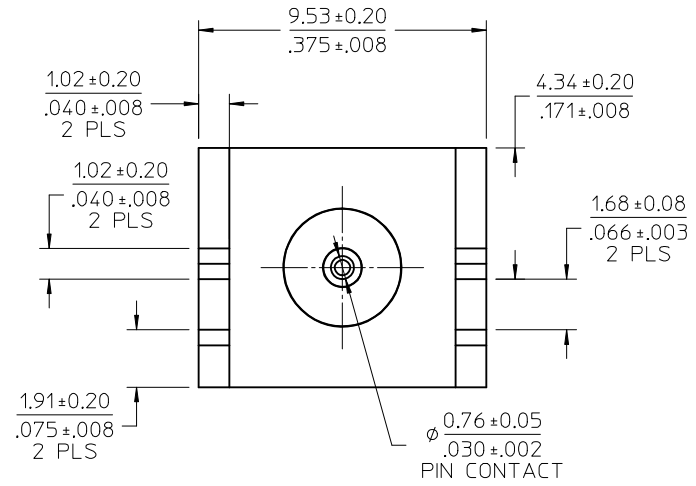
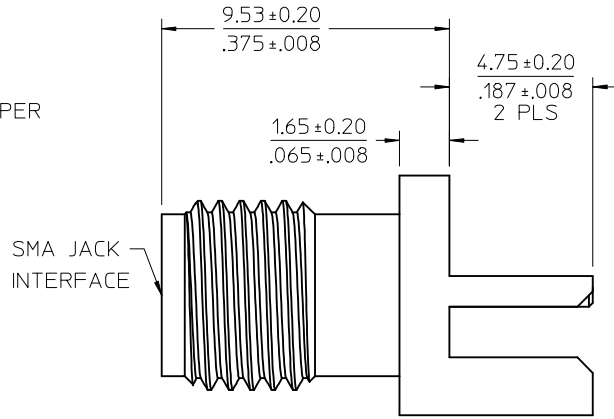


MATERIALS AND FINISHES

BODY BRASS
PLATED GOLD (SEE TABLE)

CENTER CONTACT BERYLLIUM COPPER
PLATED GOLD (SEE TABLE)

INSULATOR TEFLON



RECOMMENDED MOUNTING PAD

BASE WIDTH: 9.53(.375)
BOARD THICKNESS: 1.57(.062)
BOARD MATERIAL: FR4 W/28 g(1.0 OZ) COPPER
ON BOTTOM (GROUND) SIDE

73251-1153	GOLD FLASH	GOLD 5μ"	TRAY (80 PIECES)
73251-1152	GOLD	GOLD	TRAY (20 PIECES)
73251-1151	GOLD	GOLD	ONE 73251-1150 PER BAG
73251-1150	GOLD	GOLD	TRAY (80 PIECES)
PART NO.	BODY PLATING	CONTACT PLATING	PACKAGING

PS-89675-3460	PRODUCT SPECIFICATION
MIL-STD-348A, FIG. 310.2	INTERFACE
SPECIFICATION	DESCRIPTION

CHG: PRODUCT SPECIFICATION WAS PS-89675-2820.

EC NO: URF2014-0183
DRWIN:ROBERTSON 2013/10/09
CHKD:SSS 2013/10/09
APPR:WIENER 2013/10/10

QUALITY SYMBOLS
▽=0
▽=0

DESCRIPTION
A7

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES ±	---	---
3 PLACES ±	---	---
2 PLACES ±	---	---
1 PLACE ±	---	---

ANGULAR ± 2 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE MM/IN

SCALE

DESIGN UNITS INCH

THIRD ANGLE PROJECTION

DRAWN BY DATE
TEF 2002/06/27

CHECKED BY DATE
SSS 2002/06/27

APPROVED BY DATE
GMH 2002/06/27

MATERIAL NO. SEE TABLE

SIZE C

TITLE
SMA JACK, EDGE MOUNT
50 OHMS, EWR-1764
SMA-J/PCB

MOLEX INCORPORATED

DOCUMENT NO. SD-73251-115

SHEET NO. 1 OF 1

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